



TECHNISCHE
UNIVERSITÄT
WIEN

OXFORD
INSTRUMENTS

Workshop on Dry Processing for Nanoelectronics & Micromechanics Deposition & Etching

Oxford Instruments Plasma Technology & TU Vienna

AGENDA

Tuesday 17 September 2019

Time	Topic	Speaker
09.15 h – 10.00 h	WELCOME COFFEE & REGISTRATION	
10.00 h – 10.30 h	Dry Etching for MEMS Applications	<i>Dr Zhong Ren, Oxford Instruments</i>
10.30 h – 11.00 h	Field Emission Scanning Probe Lithography & Cryogenic Plasma Etching for beyond CMOS devices	<i>Martin Hofmann TU Ilmenau</i>
11.00 h – 11.30 h	Tuning Materials Properties in Plasma ALD by Substrate Biasing	<i>Dr Harm Knoops Oxford Instruments</i>
11:30 - 11:45	COFFEE BREAK	
11.45 h – 12.30 h	Atomic Layer Etching (ALE)	<i>Dr Matthew Loveday, Oxford Instruments</i>
12.30 h – 13.00 h	SiC Etching for Via Holes & Feature for RF & Power Applications	<i>Dr Samantha Mazzumoto, Oxford Instruments</i>
13.00 h – 14.00 h	LUNCH BREAK	
14.00 h – 14.30 h	Graphene & 2D Materials-based Devices for the Optoelectronics Industry: (PE) CVD, (PE) ALD, RIE & ALE	<i>Dr Francesco Reale, Oxford Instruments</i>
14.30 h – 15.00 h	Review of InP Etch Process Including End Point Detection & Plasma Clean Processes	<i>Dr Katie Hore, Oxford Instruments</i>
15.00 h – 15.30 h	Plasma Deposition PECVD vs ICP PECVD	<i>Dr Owain Thomas, Oxford Instruments</i>
15.30 h – 16.00	Review of AlGaAs/GaAs Processing for VCSEL Fabrication	<i>Dr Katie Hore, Oxford Instruments</i>
16.00 h – 16.30 h	Deep Etching of Interband Cascade Laser Ridge-Waveguides	<i>Johannes Hillbrand, FKE und ZMNS, TU Wien</i>
16.30 h – 18.30 h	COFFEE BREAK - POSTER SESSION – LAB TOUR	
19:00 h	CONFERENCE DINNER	



Wednesday 18 September 2019

Time	Topic	Speaker
09.30 h – 10.00 h	Etching of InP & GaAs by Ion beam Etching	<i>Dr Sebastien Pochon, Oxford Instruments</i>
10.00 h – 10.30 h	Investigation of the Transition Layer Properties of Plasma Oxidized SiC-SiO ₂ Stacks	<i>Gernot Flechl, TU Wien - ISAS</i>
10.30 h – 11.00 h	Silicon Etching for Low Loss Integrated Photonics Components	<i>Dr Zhong Ren Oxford Instruments</i>
11.00 h – 11.15 h	COFFEE BREAK	
11:15 - 11:45	Efficient Plasma Cleaning for PECVD	<i>Dr Owain Thomas, Oxford Instruments</i>
11.45 h – 12.15h	ZnO Optoelectronics using Plasma-based Processing	<i>Borislav Hinkov, FKE und ZMNS, TU Wien</i>
12.15 h – 12.45 h	Diamond Etching – Applications & Challenges	<i>Dr Andrew Newton, Oxford Instruments</i>
12.45 h - 13.45 h	LUNCH BREAK	
13.45 h – 14.15 h	GaN Low Damage Etch by ICP RIE & ALE	<i>Dr Matthew Loveday – Oxford Instruments</i>
14.15 h – 14.45 h	End Point for Ion Beam Applications Including Etching of Magnetic Materials	<i>Dr Sebastien Pochon, Oxford Instruments</i>
14.45 h – 15.15 h	Double-metal Waveguide Fabrication for High Performance THz QCLs	<i>Martin Kainz, u. ZMNS, TU Wien</i>
15.15 h – 15.30 h	COFFEE BREAK	
15.30 h - 16:00 h	Fabrication of Biomedical Devices: An Overview of Relevant Plasma Processing Technology	<i>Dr Harm Knoops – Oxford Instruments</i>
16.00 h – 16.30 h	Ion Beam Deposition of Nanolayers of VOx & other Materials	<i>Dr Sebastien Pochon, Oxford Instruments</i>
16.30 h	Final Discussion	

Cost & Accommodation

Cost Per Person: Euro 240

For coffee / lunches during the workshop hours & one dinner on 17th September

The cost will be invoiced by Oxford Instruments GmbH

Description to TU Wien

A Technische Universität Wien

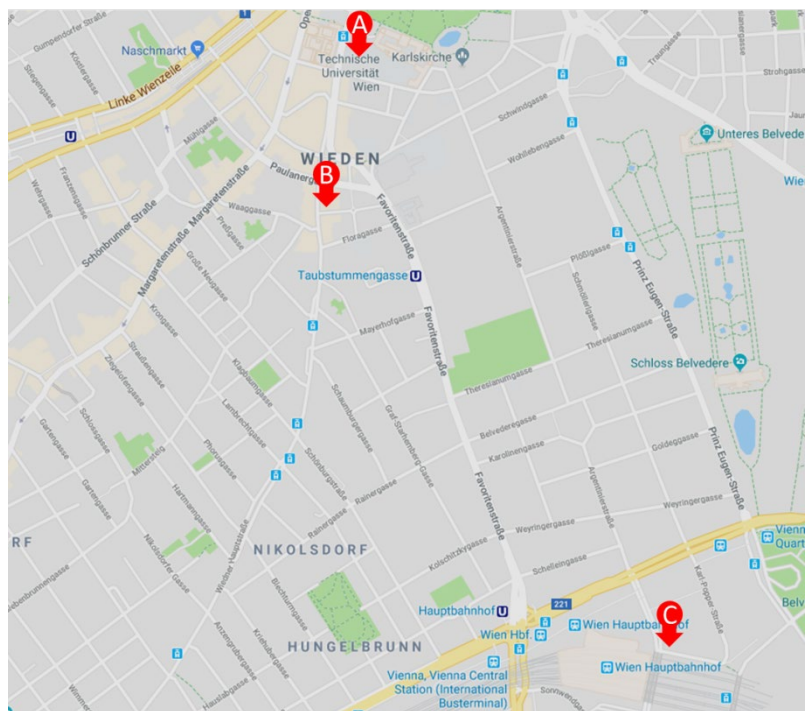
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Die Option gilt nur bis 05.08.2019. The Option is only valid until 05.08.2019